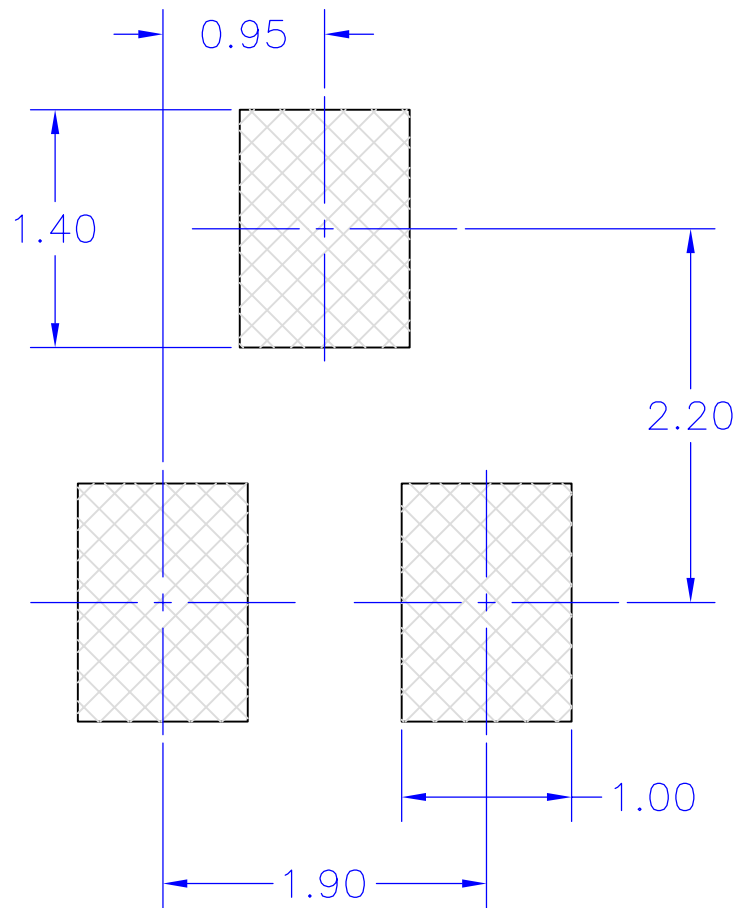
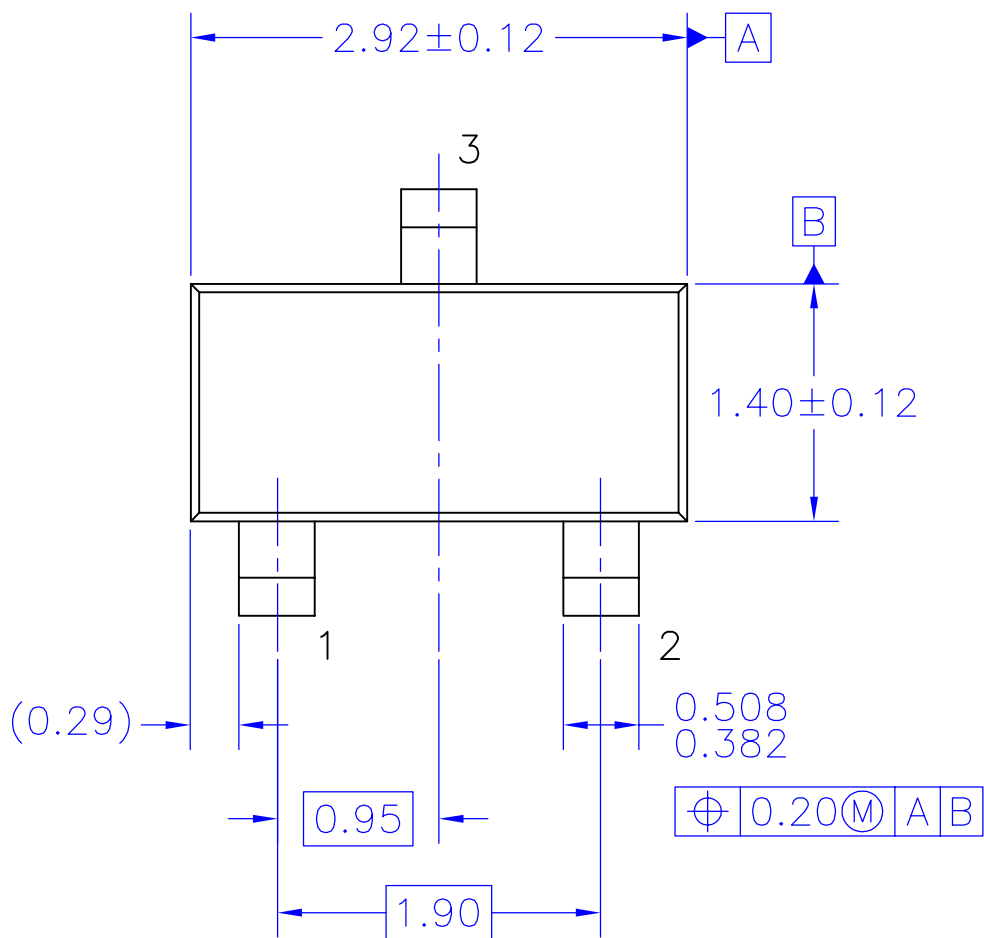


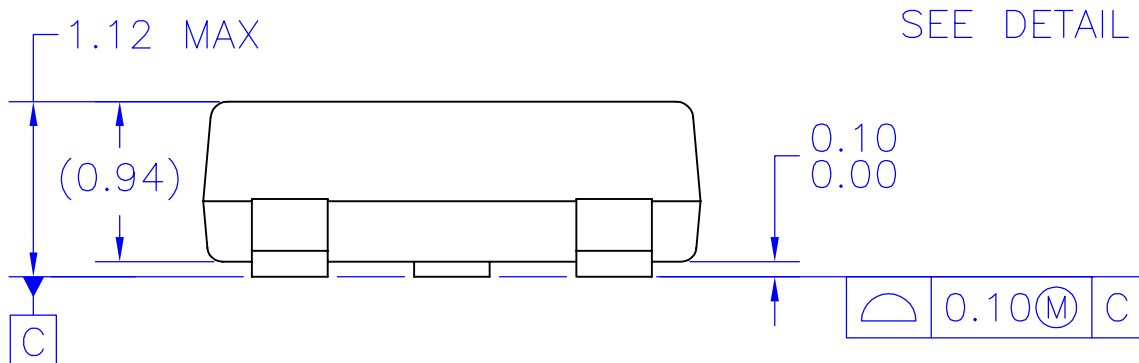
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REVISIONS

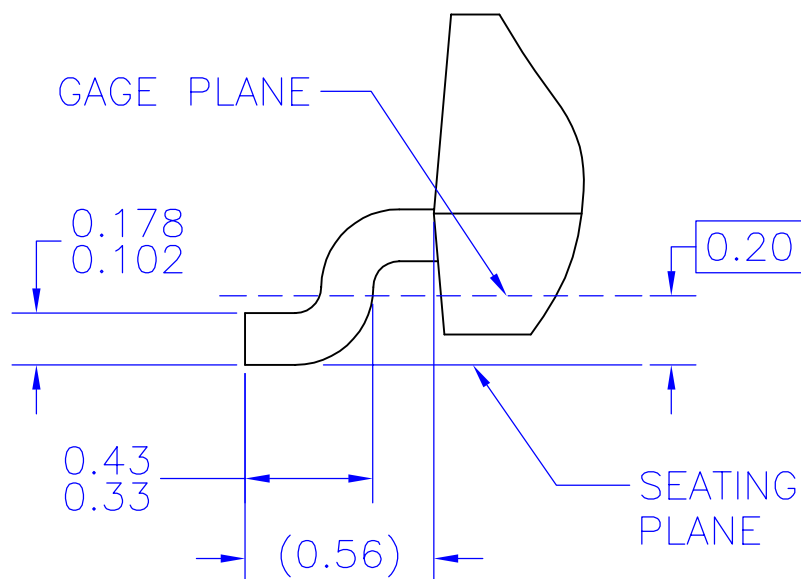
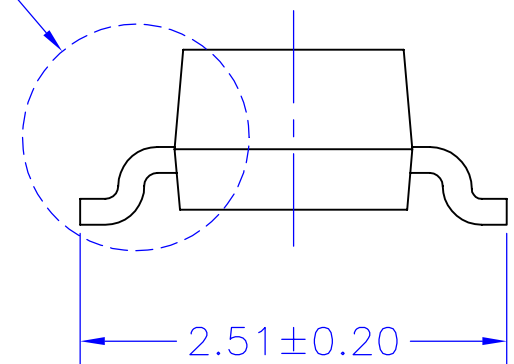
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	CB/XXX/95	NOV.30,1995	TL
B	CHG TMPT FR NSC TO FSC; CHG DIM STD FR DUAL (INCH[MM]) TO SINGLE (MM); CHG PKG WID FR 1.40±0.07 TO 1.40±0.12; CHG TOT PKG THICK FR 0.91-0.12 TO 1.12 MAX; CHG PROFILE DIM FR 0.88 TO 0.80; CHG LD SPREAD DIM FR 2.51±0.12 TO 2.51±0.20; CHG LD PITCH DIM FR 0.953±0.063 TO 0.95 BSC; CHG TOT LD PITCH FR 1.91±0.12 TO 1.90 BSC; CHG LD LNG FR 0.56 ±0.08 TO (0.56); ADD DIM (0.29); CHG LAND PTRN DIM FR 0.76 TYP TO 1.00, FR 0.76 TYP TO 1.40, FR 2.29 TO 2.20; CHG FR NOTE-1 "LEAD FINISH SPEC" TO NOTE A "JEDEC SPEC"; ADD NOTE B,C&D; ADD LD POS TOL; ADD COPLA TOL; CHG COPLA TOL FR 0.038 TO 0.10	CB/018/04	16JAN2004	MRG



LAND PATTERN RECOMMENDATION



SEE DETAIL A



DETAIL A  
SCALE: 50:1

NOTES: UNLESS OTHERWISE SPECIFIED

- A) NO JEDEC REFERENCE AS OF AUGUST 2003
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994.

MA03BREVB

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™		CEBU PHILIPPINES
DRAWN: J. GOMEZ	16JAN2004	MOLDED PACKAGE, SUPERSOT, 3 LEAD (MARKETING OUTLINE)		REV B
CHECKED: R. MANABIT				
APPROVED: M. GESTOLE				
G.S. BAJE		SCALE 25:1	A3	MKT-MA03B
PROJECTION INCH [MM]		FORMERLY: N/A	SHEET : 1 OF 1	